

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	60	Vdc
Drain-Gate Voltage ($R_{GS} = 1 \text{ M}\Omega$)	V_{DGR}	60	Vdc
Drain Current – Continuous $T_C = 25^\circ\text{C}$ (1) $T_C = 100^\circ\text{C}$ (1) – Pulsed (2)	I_D I_D I_{DM}	± 115 ± 75 ± 800	mA
Gate-Source Voltage – Continuous – Non-repetitive ($t_p \leq 50 \mu\text{s}$)	V_{GS} V_{GSM}	± 20 ± 40	Vdc Vpk
Total Power Dissipation $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$ Derate above 25°C ambient	P_D	200 80 1.6	mW mW/C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board,* $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/C
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	625	°C/W
Total Device Dissipation Alumina Substrate,** $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 2.4	mW mW/C
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	°C

*FR-5 = $1.0 \times 0.75 \times 0.062$ in.

**Alumina = $0.4 \times 0.3 \times 0.025$ in 99.5% alumina.

DEVICE MARKING

2N7002LT1 = 702

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain-Source Breakdown Voltage ($V_{GS} = 0, I_D = 10 \mu\text{A}$)	$V_{(BR)DSS}$	60	—	—	Vdc
Zero Gate Voltage Drain Current ($V_{GS} = 0, V_{DS} = 60 \text{ V}$) $T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	I_{DSS}	— —	— —	1.0 500	μA
Gate-Body Leakage Current Forward ($V_{GS} = 20 \text{ Vdc}$)	I_{GSSF}	—	—	100	nAdc
Gate-Body Leakage Current Reverse ($V_{GS} = -20 \text{ Vdc}$)	I_{GSSR}	—	—	-100	nAdc

(1) The Power Dissipation of the package may result in a lower continuous drain current.

(2) Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

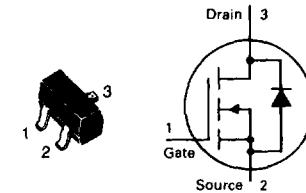
ON CHARACTERISTICS*

Gate Threshold Voltage ($V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$)	$V_{GS(\text{th})}$	1.0	—	2.5	Vdc
On-State Drain Current ($V_{DS} \geq 2.0 \text{ V}_{DS(\text{on})}, V_{GS} = 10 \text{ V}$)	$I_{D(on)}$	500	—	—	mA
Static Drain-Source On-State Voltage ($V_{GS} = 10 \text{ V}, I_D = 500 \text{ mA}$) ($V_{GS} = 5.0 \text{ V}, I_D = 50 \text{ mA}$)	$V_{DS(\text{on})}$	— —	— —	3.75 .375	Vdc
Static Drain-Source On-State Resistance ($V_{GS} = 10 \text{ V}, I_D = 500 \text{ mA}$) $T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$ ($V_{GS} = 5.0 \text{ V}, I_D = 50 \text{ mA}$) $T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$	$r_{DS(\text{on})}$	— — — —	— — — —	7.5 13.5 7.5 13.5	Ohms
Forward Transconductance ($V_{DS} \geq 2.0 \text{ V}_{DS(\text{on})}, I_D = 200 \text{ mA}$)	g_{FS}	80	—	—	mmhos

Rev 1

2N7002LT1★

CASE 318-07 STYLE 21
SOT-23 (TO-236AB)



**TMOS FET
TRANSISTOR**

N-CHANNEL

★This is a Motorola
designated preferred device.

Refer to 2N7000 for graphs.

2N7002LT1

ELECTRICAL CHARACTERISTICS (continued) ($T_A = 25^\circ\text{C}$ unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
DYNAMIC CHARACTERISTICS					
Input Capacitance ($V_{DS} = 25\text{ V}$, $V_{GS} = 0$, $f = 1.0\text{ MHz}$)	C_{iss}	—	—	50	pF
Output Capacitance ($V_{DS} = 25\text{ V}$, $V_{GS} = 0$, $f = 1.0\text{ MHz}$)	C_{oss}	—	—	25	pF
Reverse Transfer Capacitance ($V_{DS} = 25\text{ V}$, $V_{GS} = 0$, $f = 1.0\text{ MHz}$)	C_{rss}	—	—	5.0	pF
SWITCHING CHARACTERISTICS*					
Turn-On Delay Time ($V_{DD} = 25\text{ V}$, $I_D \geq 500\text{ mA}$, $R_G = 25\Omega$, $R_L = 50\Omega$)	$t_{d(on)}$	—	—	30	ns
Turn-Off Delay Time	$t_{d(off)}$	—	—	40	ns
BODY-DRAIN DIODE RATINGS					
Diode Forward On-Voltage ($I_S = 11.5\text{ mA}$, $V_{GS} = 0\text{ V}$)	V_{SD}	—	—	-1.5	V
Source Current Continuous (Body Diode)	I_S	—	—	-115	mA
Source Current Pulsed	I_{SM}	—	—	-800	mA

*Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2.0\%$.